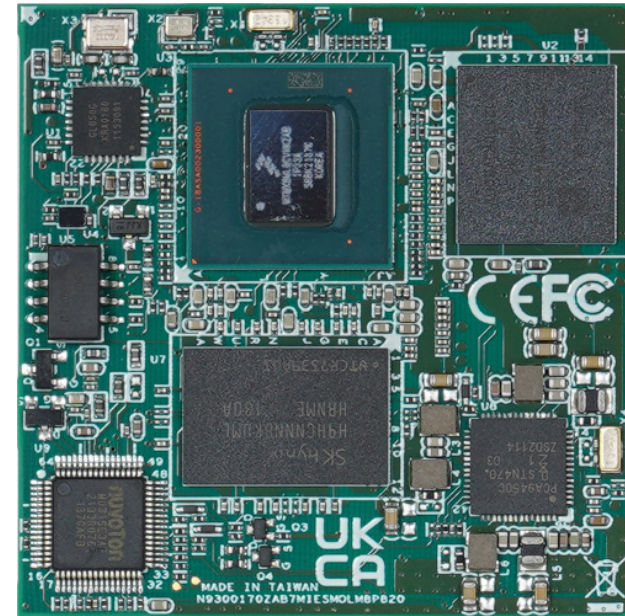


# Embedded Module

Open Standard Module™ - iesy i.MX8M Plus OSM-LF

## Technical Concept

- ▶ Processor: NXP i.MX8M Plus
- ▶ RAM: 2GB
- ▶ Flash-Memory: 16GB eMMC
- ▶ Dimension: 45 mm x 45 mm
- ▶ Footprint: OSM Size-L  
Land Grid Array (LGA) with 662 contacts
- ▶ Power-Supply: 5V via LGA Kontakte
- ▶ Software: Linux based BSP (Yocto)
- ▶ Temperature:
  - > Operating: -40 °C to +85 °C
  - > Storage: -40 °C to +85 °C
- ▶ Features & Interfaces
  - > 2x Ethernet
  - > 4x USB 2.0
  - > 1x USB 3.0
  - > 4x UART
  - > 8x GPIO
  - > 2x SPI
  - > 2x I2c
  - > 1x I2S
  - > 2x SDIO
  - > 2x CAN
  - > 1x JTAG
  - > 4x PWM
  - > 1x DSi, 1x CSI
  - > 1x PCIe
  - > 1x HDMI
  - > 1x LVDS



## About OSM™

The Open Standard Modules™ specification was adopted by the SGeT e.V. in 2019. The new standard was developed to meet future requirements in terms of **flexibility**, **scalability**, but also **costs**. OSM™ solder-down modules can be **individually adapted** to the respective customer requirements. For this purpose, the individual modules can be made **available to the SMT process** by means of tray & reel packaging and processed automatically. The OSM™ series includes in total four different form factors.



[iesy.com/osm](http://iesy.com/osm)